



Statement of Materials, Construction

44 LQFP(10x10) TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Ag Plated Cu	0.40360	Cu	7440-50-8	0.38080	0.626	94.35
				Fe	7439-89-6	0.00081	0.001	0.20
				Ni	7440-02-0	0.01292	0.021	3.20
				Zn	7440-32-6	0.00404	0.007	1.00
				Pb	7439-92-1	0.00020	0.000	0.05
				Mn	7439-96-5	0.00040	0.001	0.10
				Si	7440-21-3	0.00293	0.005	0.73
				Silver (plating)	7440-22-4	0.00081	0.001	0.20
2	Die	Silicon Chip	0.01200	Mg	7439-95-4	0.00071	0.001	0.18
				Si	7440-21-3	0.01194	0.020	99.50
3	Die Attach Material	Conductive Epoxy	0.00230	Epoxy Resin	Proprietary	0.00035	0.001	15.00
				Silver	7440-22-4	0.00183	0.003	79.50
4	Wire	Gold	0.0004	Aromatic Amine	Proprietary	0.00013	0.000	5.50
				Au	7440-57-5	0.00040	0.001	99.99
5	Lead Finish	Pb	0.0037	Pb	7439-92-1	0.00037	0.001	10.00
		Tin		Sn	7440-31-5	0.00333	0.005	90.00
6	Encapsulation	Epoxy Resin	0.1859	Fused Silica	60676-86-0	0.15188	0.250	81.70
				Epoxy resin	Proprietary	0.01394	0.023	7.50
				Phenol Resin	Proprietary	0.01394	0.023	7.50
				Brominated Epoxy Resin	68541-56-0	0.00279	0.005	1.50
				Carbon Black	1333-86-4	0.00056	0.001	0.30
				Antimony Trioxide	1309-64-4	0.00279	0.005	1.50
Total Package Weight			0.60790					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit
Lead	1000 ppm
Mercury	1000 ppm
Cadmium	100 ppm
Hexavalent Chromium	1000 ppm
Polybrominated Biphenyls (PBB)	1000 ppm
Polybrominated Biphenylethers (PBDE)	1000 ppm